

# APPLICATION DATA SHEET

## INVENTOR INFORMATION

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## CORRESPONDENCE INFORMATION

Correspondence customer number: 23911

## APPLICATION INFORMATION

Title line one:	SEMICONDUCTOR WAFER AND
Title line two:	APPARATUS OF PROCESS FOR
Title line three:	FABRICATING SEMICONDUCTOR
Title line four:	DEVICES
Total drawing sheets:	11
Formal drawings?:	Yes
Application type:	Utility
Docket Number:	155/50674

## REPRESENTATIVE INFORMATION

Representative customer number: 23911

## CONTINUITY INFORMATION

This application is a:	371 of
Application one:	PCT/JP01/03635
Filing date:	April 26, 2001
Patent number:	

## PRIOR FOREIGN APPLICATIONS

Foreign application one:	2000-128502
Filing date:	April 27, 2000
Country:	Japan
Priority claimed:	Yes